

Report Generated From Altium Designer

Name	Priority	Enabled	Type	Category	Scope	Attributes
AssemblyTestpoint	1	True	Assembly Testpoint Style	Testpoint	All	Under Comp - Allow Sides - Top, Bottom Pref Size = 1.524mm Pref Hole Size = 0.813mm Using Grid = Yes Grid = 0.025mm Grid Tolerance = 0mm
AssemblyTestPointUsage	1	True	Assembly Testpoint Usage	Testpoint	All	Testpoint - One Required Multiple - Not Allowed
FabricationTestpoint	1	True	Fabrication Testpoint Style	Testpoint	All	Under Comp - Allow Sides - Top, Bottom Pref Size = 1.524mm Pref Hole Size = 0.813mm Using Grid = Yes Grid = 0.025mm Grid Tolerance = 0mm
FabricationTestPointUsage	1	True	Fabrication Testpoint Usage	Testpoint	All	Testpoint - One Required Multiple - Not Allowed
SMDEntry	2	True	SMD Entry	SMT	All	Side = Allowed Corner = Allowed Any Angle = Not Allowed Ignore First Corner = Allowed
SMDEntry-GND	1	True	SMD Entry	SMT	InNet('GND')	Side = Allowed Corner = Not Allowed Any Angle = Not Allowed Ignore First Corner = Allowed
DiffPairsRouting	2	True	Differential Pairs Routing	Routing	All	Pref Gap = 0.2mm Min Gap = 0.15mm Max Gap = 0.25mmPref Width = 0.25mm Min Width = 0.15mm Max Width = 0.25mm
EthernetDiffPair	1	True	Differential Pairs Routing	Routing	InDifferentialPairClass('All Differential Pairs')	Pref Gap = 0.151mm Min Gap = 0.151mm Max Gap = 0.151mmPref Width = 0.3mm Min Width = 0.3mm Max Width = 0.3mm
Fanout_BGA	1	True	Fanout Control	Routing	IsBGA	Style - Auto Direction - Alternating In and Out Via Grid = 0.025mm
Fanout_Default	5	True	Fanout Control	Routing	All	Style - Auto Direction - Alternating In and Out Via Grid = 0.025mm
Fanout_LCC	2	True	Fanout Control	Routing	IsLCC	Style - Auto Direction - Alternating In and Out Via Grid = 0.025mm
Fanout_Small	4	True	Fanout Control	Routing	(CompPinCount < 5)	Style - Auto Direction - Out Then In Via Grid = 0.025mm
Fanout_SOIC	3	True	Fanout Control	Routing	IsSOIC	Style - Auto Direction - Alternating In and Out Via Grid = 0.025mm
RoutingCorners	1	True	Routing Corners	Routing	All	Style - 45 Degree Min Setback = 2.5mm Max Setback = 2.5mm
RoutingLayers	1	True	Routing Layers	Routing	All	TopLayer - Enabled BottomLayer - Enabled
RoutingPriority	1	True	Routing Priority	Routing	All	Priority = 0
RoutingTopology	1	True	Routing Topology	Routing	All	Topology - Shortest
RoutingViasES	1	True	Routing Via Style	Routing	All	Pref Size = 0.51mm Pref Hole Size = 0.25mm
Width-230VAC	1	True	Width	Routing	InNetClass('AC-230V')	Pref Width = 1.5mm Min Width = 1mm Max Width = 10mm
Width-3V3	2	True	Width	Routing	InNet('+3V3')	Pref Width = 0.3mm Min Width = 0.25mm Max Width = 1mm
Width-xTW	3	True	Width	Routing	All	Pref Width = 0.2mm Min Width = 0.15mm Max Width = 1.5mm
GND-CONNECT	1	True	Polygon Connect Style	Plane	All - InNet('GND')	Advanced settings
PlaneClearance-IPI	1	True	Power Plane Clearance	Plane	All	Clearance = 0.25mm
PlaneConnect	1	True	Power Plane Connect Style	Plane	All	Style - Relief Connect Expansion = 0.175mm Width = 0.2mm Gap = 0.2mm # Entries = 4

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PolygonConnect-xTW	2	True	Polygon Connect Style	Plane	All - All	Advanced settings
ComponentClearance	1	True	Component Clearance	Placement	All - All	Horizontal Clearance = 0.1mm Vertical Clearance = 0.25mm
Height	1	True	Height	Placement	All	Pref Height = 12.5mm Min Height = 0mm Max Height = 25mm
PasteMaskExpansion	1	True	Paste Mask Expansion	Mask	All	Expansion = -0.025mm
SolderMaskExpansion	1	True	Solder Mask Expansion	Mask	All	Expansion = 0mm
BoardOutlineClearance	1	True	Board Outline Clearance	Manufacturing	All	Generic clearance = 0.25mm, and 9 value(s) for objects
HoleSize-PTH	1	True	Hole Size	Manufacturing	All	Min = 0.25mm Max = 10mm
HoleToHoleClearance	1	True	Hole To Hole Clearance	Manufacturing	All - All	Hole To Hole Clearance = 0.35mm
LayerPairs	1	True	Layer Pairs	Manufacturing	All	Layer Pairs - Enforce
Minimum IAR >0.45mm	1	True	Minimum Annular Ring	Manufacturing	((ObjectKind = 'Pad') OR (ObjectKind = 'Via')) And (Layer = 'MultiLayer') And (HoleDiameter > AsMM(0.45))	Min = 0.15mm
Minimum IAR <=0.45mm	2	True	Minimum Annular Ring	Manufacturing	((ObjectKind = 'Pad') OR (ObjectKind = 'Via')) And (Layer = 'MultiLayer') And (HoleDiameter <= AsMM(0.45))	Min = 0.125mm
MinimumSolderMaskSliver	1	True	Minimum Solder Mask Sliver	Manufacturing	All - All	Minimum Solder Mask Sliver = 0.08mm
NetAntennae	1	True	Net Antennae	Manufacturing	All	Net Antennae Tolerance = 2mm
SilkscreenOverComponentPads	1	True	Silk To Solder Mask Clearance	Manufacturing	IsPad - All	Silk To Solder Mask Clearance = 0.2mm
SilkToSilkClearance	1	True	Silk To Silk Clearance	Manufacturing	All - All	Silk to Silk Clearance = 0.2mm
Clearance 230VAC-230VAC	1	True	Clearance	Electrical	InNetClass('AC-230V') - InNetClass('AC-230V')	Clearance = 2.5mm
Clearance-230VAC-ALL	2	True	Clearance	Electrical	All - InNetClass('AC-230V')	Clearance = 4mm
Clearance-xPP-xTP-xTT	3	True	Clearance	Electrical	All - All	Clearance = 0.151mm
ShortCircuit	1	True	Short-Circuit	Electrical	All - All	Short Circuit - Not Allowed
UnpouredPolygon	1	True	Modified Polygon	Electrical	All	Allow modified - No Allow shelved - No
UnRoutedNet	1	True	Un-Routed Net	Electrical	All	(No Attributes)